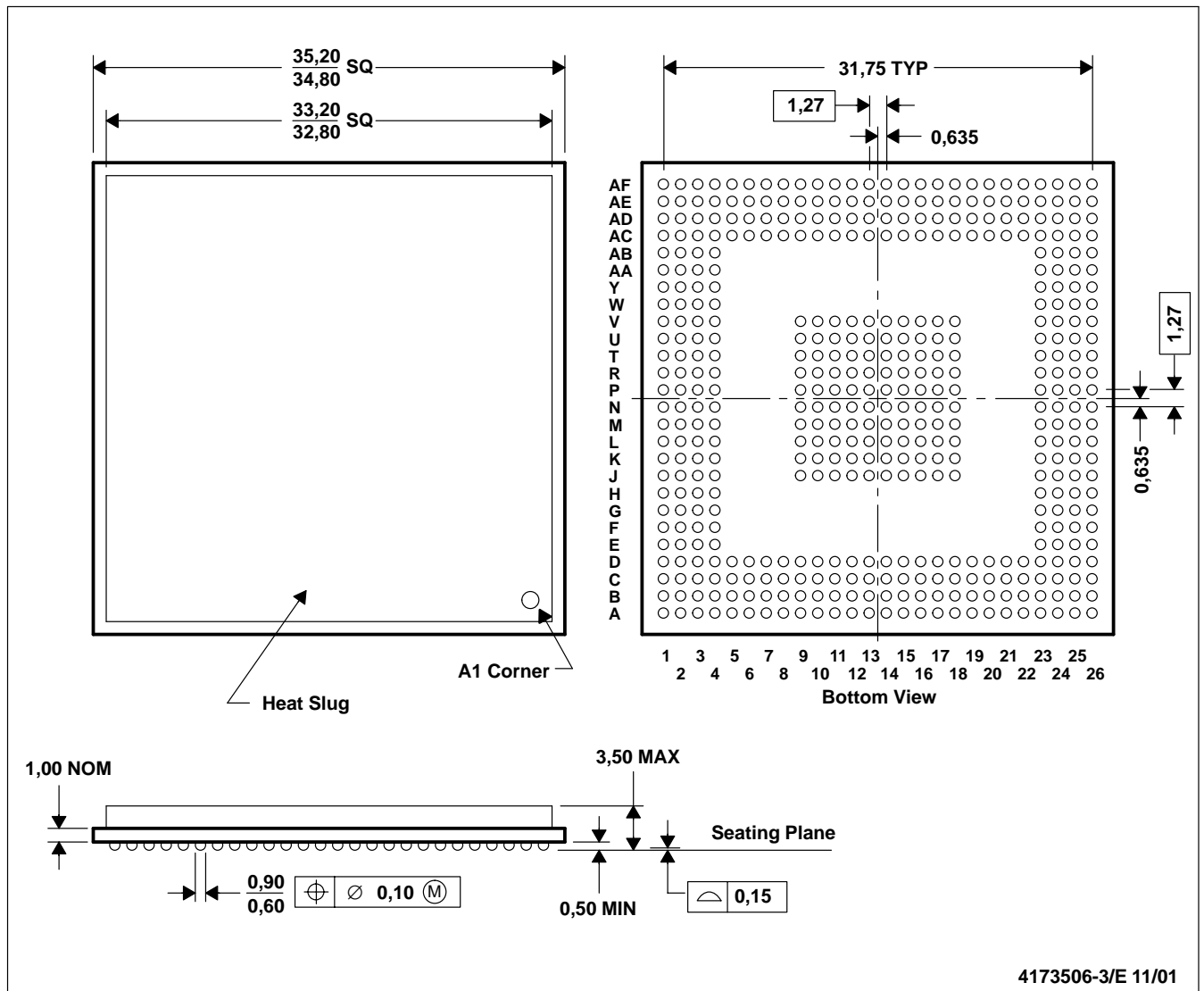


GJC (S-PBGA-N452)

PLASTIC BALL GRID ARRAY



4173506-3/E 11/01

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Thermally enhanced plastic package with heat slug (HSL).
  - D. Falls within JEDEC MO-151/BAR-2
  - E. Flip chip application only.

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### Mailing Address:

Texas Instruments  
Post Office Box 655303  
Dallas, Texas 75265